

Description

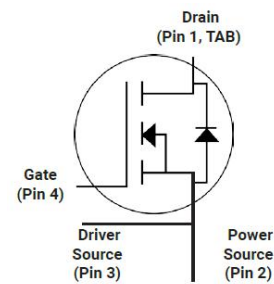
Silicon Carbide (SiC) MOSFET use a completely new technology that provide superior switching performance and higher reliability compared to Silicon. In addition, the low ON resistance and compact chip size ensure low capacitance and gate charge. Consequently, system benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size.

Features

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low RDS(on)
- Simple to drive with Standard Gate Drive
- 100% avalanche tested
- Maximum junction temperature of 150°C
- ROHS Compliant

Application

- EV Charging
- DC-AC Inverters
- High Voltage DC/DC Converters
- Switch Mode Power Supplies
- Power Factor Correction Modules
- Motor Drives



Ordering Information

Part Number	Marking	Package	Packaging
JX4S0020090M	JX4S0020090M	TO-247	Tube

Absolute Maximum Ratings(Tc=25°C)

Symbol	Parameter	Value	Unit
V _{DS}	Drain-Source Voltage	900	V
I _D	Drain Current(continuous)at Tc=25°C	100	A
I _D	Drain Current(continuous)at Tc=100°C	70	A
I _{DM}	Drain Current (pulsed)	200	A
V _{GS}	Gate-Source Voltage	-10/+20	V
P _D	Power Dissipation T _c = 25°C	425	W
T _J , T _{stg}	Junction and Storage Temperature Range	-55 to +150	°C

Electrical Characteristics(T_J = 25°C unless otherwise specified)
Typical Performance-Static

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV _{DS}	Drain-source Breakdown Voltage	I _D =250uA, V _{GS} =0V	900			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =900V, V _{GS} =0V, T _J =25°C			100	uA
I _{GSS}	Gate-body Leakage Current	V _{DS} =0V ; V _{GS} =10 to 20V			250	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =15mA	2		4	V
R _{D(son)}	Static Drain-source On Resistance	V _{GS} =20V, I _D =50A		16	22	mΩ
R _G	Gate Resistance	V _{GS} =0V, f=1MHz		3		Ω

Typical Performance-Dynamic

C _{iss}	Input Capacitance	V _{DS} =600V, f=1000KHz, V _{GS} =0V		4910		pF
C _{oss}	Output Capacitance			129		pF
C _{rss}	Reverse Transfer Capacitance			27		pF
Q _g	Total Gate Charge	V _{DS} =600V, I _D =50A, V _{GS} =-4~20V		167		nC
Q _{gs}	Gate-source Charge			58		nC
Q _{gd}	Gate-Drain Charge			47		nC
t _{d(on)}	Turn-on Delay Time	V _{DD} =600V, I _D =50A, V _{GS} =-4V~20V, R _G =0Ω,		157		ns
t _r	Rise Time			28		ns
t _{d(off)}	Turn-off Delay Time			81		ns
t _f	Fall Time			27		ns

Typical Performance-Reverse Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{FSD}	Forward Voltage	V _{GS} =0V, I _F =30A, T _J =25°C	3		6	V
		V _{GS} =0V, I _F =30A, T _J =150°C	3		6	V
t _{rr}	Reverse Recovery Time	V _{GS} =0 V, I _F =30 A, V _R =600 V, di/dt= 100 A/μs		86		ns
Q _{rr}	Reverse Recovery Charge			876		nC
I _{rrm}	Peak Reverse Recovery Current			20		A

Thermal Characteristics

Symbol	Parameter	Value.	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	0.3	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Case	40	°C/W

The values are based on the junction-to case thermal impedance which is measured with the device mounted to a large heat sink assuming maximum junction temperature of T_J(max)=150°C

●Electrical characteristic curves

Fig.1 Typical Output Characteristics(I)

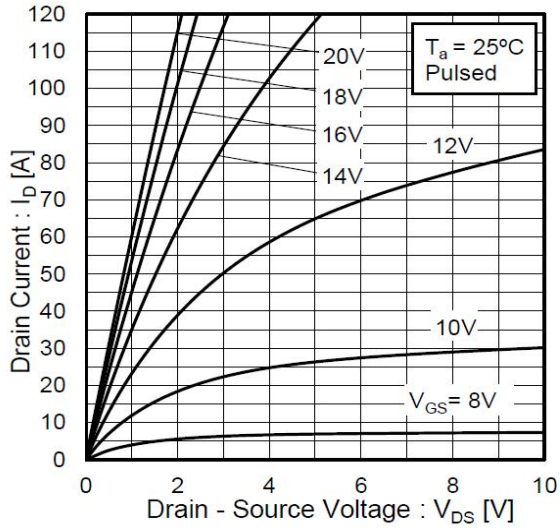


Fig.2 Typical Output Characteristics(II)

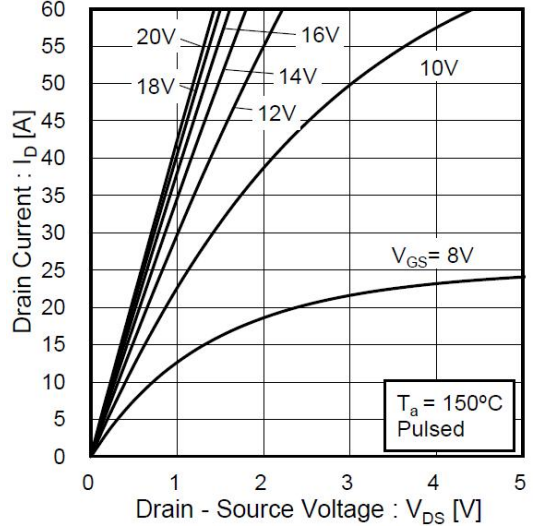


Figure 3. Normalized On-Resistance vs. Tj

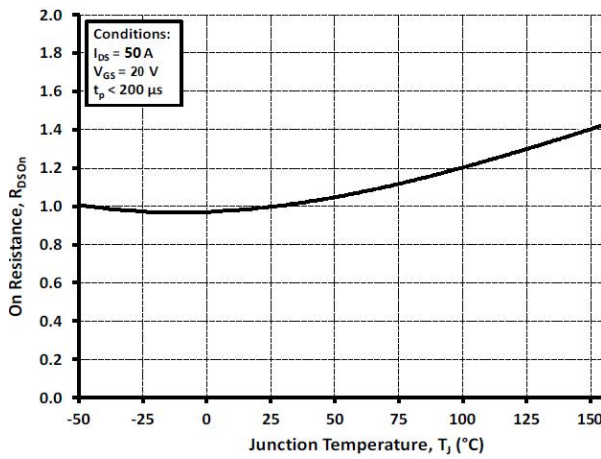


Figure 4. On-Resistance vs. Drain Current

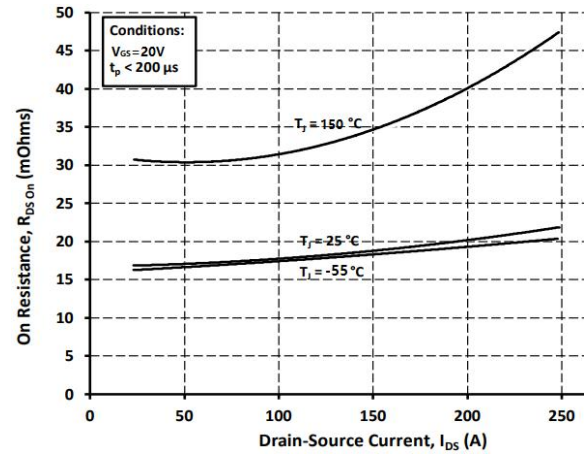


Figure 5. Transfer Characteristic for Various Tj

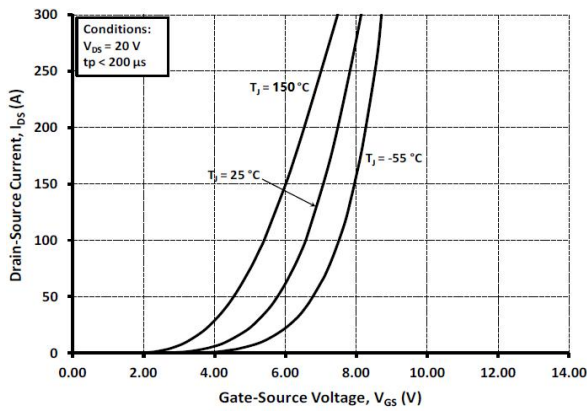


Figure 6. Body Diode Characteristic

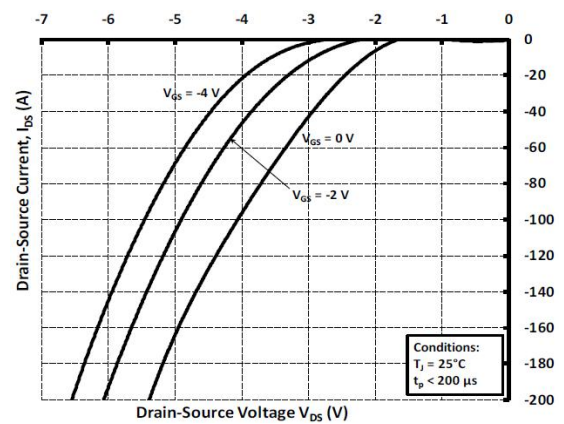


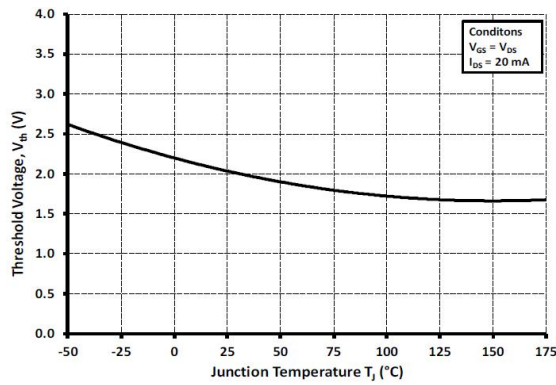
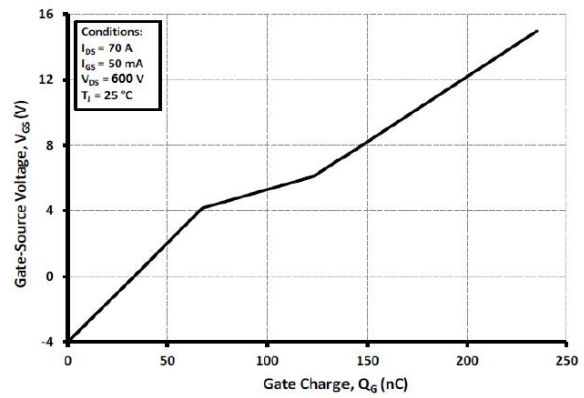
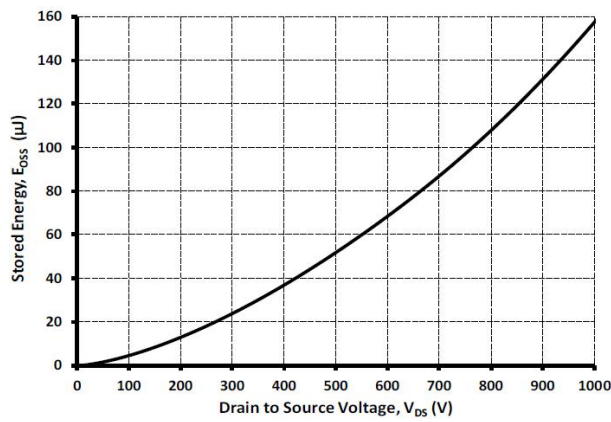
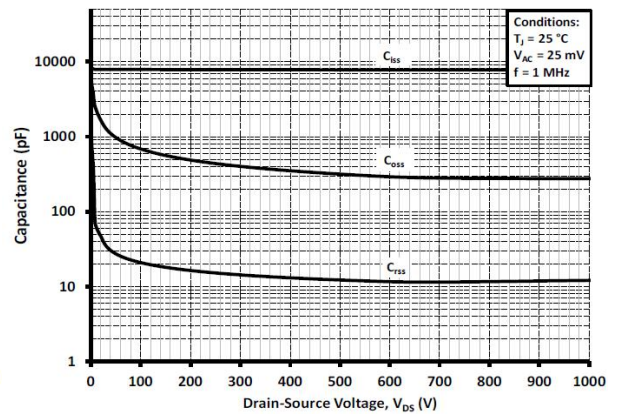
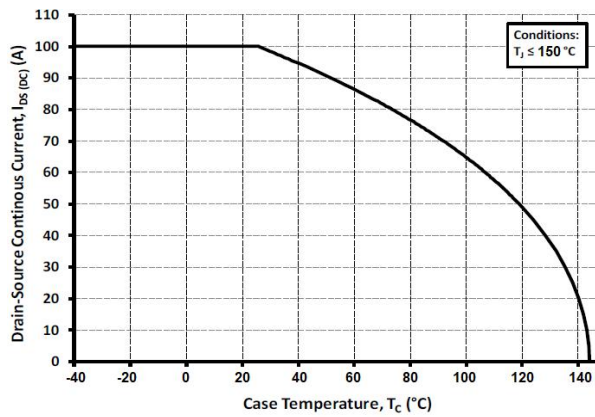
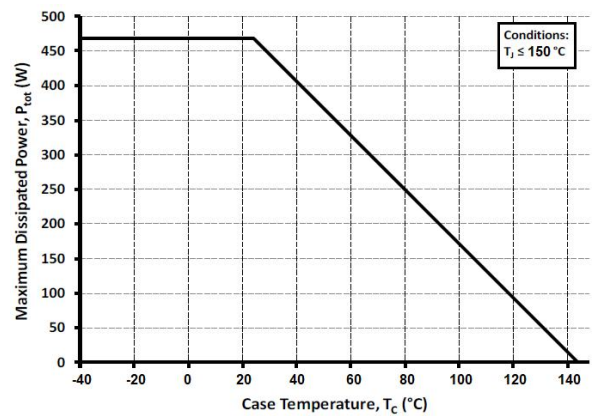
Figure 7. Threshold Voltage vs. T_j

Figure 8. Gate Charge Characteristics

Figure 9. Output Capacitor Stored Energy

Figure 10. Capacitances vs. V_{DS}

Figure 11. Continuous Drain Current vs. T_c

Figure 12. Maximum Power vs. T_c


Figure 13. Transient Thermal Impedance

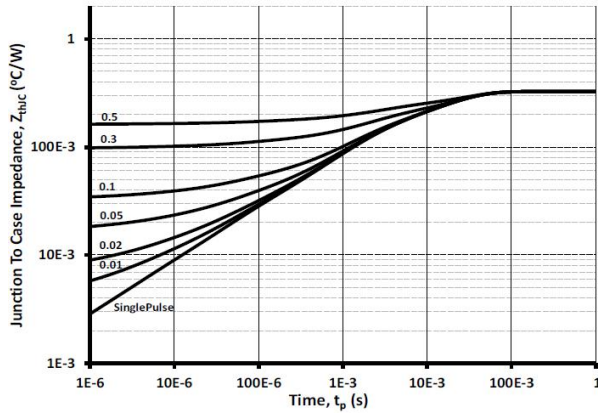


Figure 14. Safe Operating Area

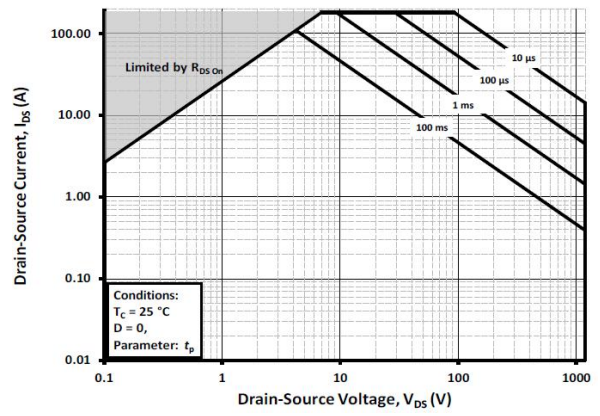


Figure 15. Switching Energy vs. $R_G(\text{ext})$

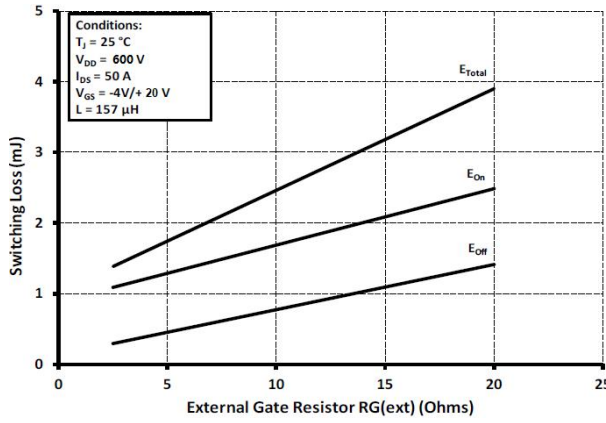
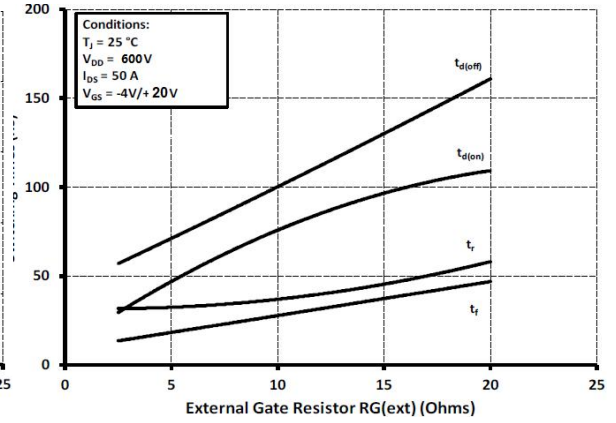
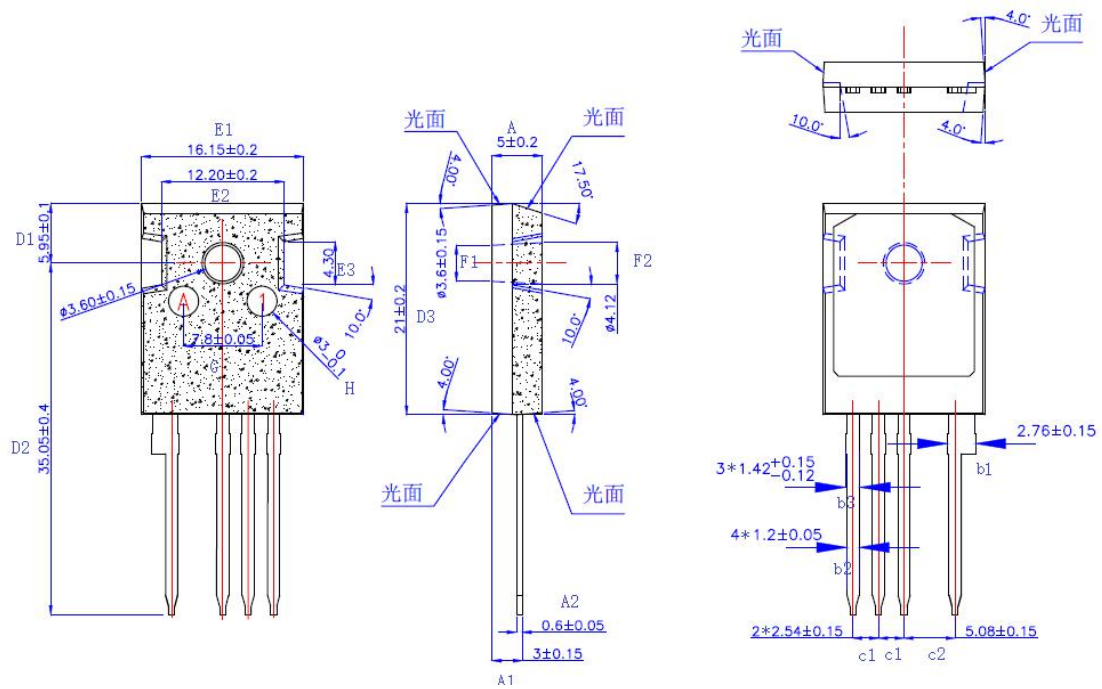


Figure 16. Switching Times vs. $R_G(\text{ext})$



Package Drawing:

Dimensions (UNIT: mm)

SYM	MILLIMETERS		SYM	MILLIMETERS	
	MIN	MAX		MIN	MAX
A	4.98	5.02	D2	34.65	35.45
A1	2.85	3.15	D3	20.80	21.20
A2	0.55	0.65	E1	15.95	16.35
b1	2.61	2.91	E2	12.00	12.40
b2	1.15	1.25	F1	3.45	3.75
b3	1.30	1.57	F2	4.12	4.12
c1	2.39	2.69	G	7.75	7.85
c2	4.93	5.23	H	2.90	3.10
D1	5.85	6.05			